Number	""	ts Search Text	DB	Time stamp
62		(providing near3 substrate) and		me scamp
			USPAT;	2002/07/12
1		((attaching soldering) near3 pin) and (encapsulant encapsulation)	US-PGPUB	; 16:18
1		(encapsulant encapsulating encapsulated sealing)	EPO; JPO	;
63	1	2 ("5249100" "6300678").PN.	DERWENT	
	1	·15200 03006/8").PN.	USPAT	2002/07/12
64		6 5249100.URPN.		15:58
		TELESTOO. ORFIN.	USPAT	2002/07/12
		4 ("3645785" "3055602" "3055	_	15:59
		4 ("3645785" "3855693" "4702941" "4918811").PN.	USPAT	2002/07/12
66	ļ	1 6300678.URPN.		15:59
		1 0300078.URPN.	USPAT	2002/07/12
67		9 ("4949455" "5041001" "5555	122.12	16:00
	1	1 1 -7 -7 -7 -7 1 3041901" "6061660"	USPAT	
	1		JULIA	2002/07/12
68	1	1 3333003" "5642261" #E010E10#;		16:00
	-	" \ "" "" "" " " " " " " "	USPAT	10000 1000
	I	1 3443404" 1 "5334804" 1 "6410007" 1	USPAT	2002/07/12
69	1	1 333003" "5642261" "5013510"		16:02
09		0 6413849.URPN.	*****	
70			USPAT	2002/07/12
70	8			16:02
		J440UID	USPAT	2002/07/12
	1	"6054652" "6077725").PN.		16:03
	17	5640052.URPN.	1	
	1		USPAT	2002/07/12
72	2	6054652.URPN.		16:04
			USPAT	2002/07/12
73	8	("4634041" "4070570"		16:08
	Ŭ		USPAT	2002/07/12
ł		"5448016" "5640052" "5718367"	1	16:09
74	0	1 0034632 "60///25") PN		10.09
	Ū	0413649.URPN.	USPAT	2002/07/10
75	0	(11463494911)	951111	2002/07/12
/3	8		USPAT	16:09
į		3448016" "5640052" "5710267"	OSPAI	2002/07/12
76		1 0034032" "6077725" DM		16:09
76	4	("5421083" "5432675" "5542596"	*****	
77		1 3034/05").PN.	USPAT	2002/07/12
77	5986	I (P GG) GIIG GG (AFFAV) NASI SSA		16:09
		(method process)	USPAT;	2002/07/12
1		•	US-PGPUB;	16:14
_			EPO; JPO;	
78	170	(((pin adj grid adj array) pga) and	DERWENT	
		(method process)) and jig	USPAT;	2002/07/12
		F	US-PGPUB;	16:14
	İ		EPO; JPO;	
79	55	((((pin adi grid adi a	DERWENT	
		((((pin adj grid adj array) pga) and	USPAT;	2002/07/12
		(method process)) and jig) and polymer	US-PGPUB;	16:14
			EPO; JPO;	
30	51	((((hip adi mid))	DERWENT	j
	51	(((((pin adj grid adj array) pga) and	USPAT;	2002/07/12
1	ĺ	(Mechod process)) and fig and males.	US-PGPUB;	16:15
1		1100 ((DIOVIGING Dears substrate)	EPO; JPO;	10.13
		\\accacliffig Soldering) near3 min\1	DERWENT	
		tendapsulant encapsulating encapsulated		i
1	10	searring))		
-	12	((((((pin adj grid adj array) pga) and	USPAT;	2002/07/75
-	1	(metriod process)) and iid) and males of	US-PGPUB;	2002/07/12
	ĺ	"" ((Providing near) substrato) and	EPO; JPO;	16:16
		((accaching Soldering) near? nin(DERWENT	
	i	(elicapsulant encapsulating encapsulated	DEKMENT.	[
		sealing))) and substrate and solder and]	1
	1.1	pad		
?	107	(providing near3 substrate) and		
	1	((attaching soldering) near3 pin)	USPAT;	2002/07/12
1	1	= :	US-PGPUB;	16:18
	1		EPO; JPO;	I
			DERWENT	i

83	18	(providing near3 substrate) and ((attaching soldering) near3 pin) and (applying near3 polymer) ((attaching soldering) near3 pin) and (applying near3 (polymer polymeric polymeric)	US-PGPUB;	2002/07/12 16:31 2002/07/12 16:33
		1 11 12 12 12 17 1	EPO; JPO; DERWENT	10.33